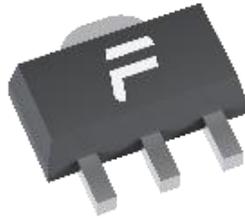
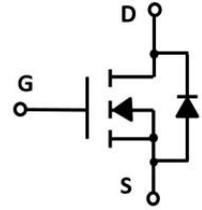
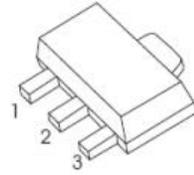


**SOT-89-3L 30V N Channel Enhancement 沟道增强型  
MOS Field Effect Transistor 场效应管**



- 1. Gate
- 2. Drain
- 3. Source



**■ Absolute Maximum Ratings 最大额定值**

Characteristic 特性参数	Symbol 符号	Rat 额定值	Unit 单位
Drain-Source Voltage 漏极-源极电压	$BV_{DSS}$	30	V
Gate- Source Voltage 栅极-源极电压	$V_{GS}$	$\pm 12$	V
Drain Current (continuous)漏极电流-连续	$I_D$ (at $T_A = 25^\circ C$ )	5.8	A
Drain Current (pulsed)漏极电流-脉冲	$I_{DM}$	23	A
Total Device Dissipation 总耗散功率	$P_D$ (at $T_A = 25^\circ C$ )	1400	mW
Thermal Resistance Junction-Ambient 热阻	$R_{\theta JA}$	90	$^\circ C/W$
Junction/Storage Temperature 结温/储存温度	$T_J, T_{stg}$	-55~150	$^\circ C$

**■ Device Marking 产品字标**

**FS3400F=3400**

**Electrical Characteristics 电特性**

 (T<sub>A</sub>=25°C unless otherwise noted 如无特殊说明, 温度为 25°C)

Characteristic 特性参数	Symbol 符号	Min 最小值	Typ 典型值	Max 最大值	Unit 单位
Drain-Source Breakdown Voltage 漏极-源极击穿电压(I <sub>D</sub> =250uA, V <sub>GS</sub> =0V)	BV <sub>DSS</sub>	30	—	—	V
Gate Threshold Voltage 栅极开启电压(I <sub>D</sub> =250uA, V <sub>GS</sub> =V <sub>DS</sub> )	V <sub>GS(th)</sub>	0.65	0.9	1.5	V
Zero Gate Voltage Drain Current 零栅压漏极电流(V <sub>GS</sub> =0V, V <sub>DS</sub> =30V)	I <sub>DSS</sub>	—	—	1	uA
Gate Body Leakage 栅极漏电流(V <sub>GS</sub> =±12V, V <sub>DS</sub> =0V)	I <sub>GSS</sub>	—	—	±100	nA
Static Drain-Source On-State Resistance 静态漏源导通电阻(I <sub>D</sub> =5.8A, V <sub>GS</sub> =10V) (I <sub>D</sub> =5A, V <sub>GS</sub> =4.5V) (I <sub>D</sub> =3A, V <sub>GS</sub> =2.5V)	R <sub>DS(ON)</sub>	—	21 25 33	27 33 51	mΩ
Diode Forward Voltage Drop 内附二极管正向压降(I <sub>SD</sub> =5.6A, V <sub>GS</sub> =0V)	V <sub>SD</sub>	—	—	1.2	V
Input Capacitance 输入电容 (V <sub>GS</sub> =0V, V <sub>DS</sub> =15V, f=1MHz)	C <sub>ISS</sub>	—	630	—	pF
Common Source Output Capacitance 共源输出电容(V <sub>GS</sub> =0V, V <sub>DS</sub> =15V, f=1MHz)	C <sub>OSS</sub>	—	55	—	pF
Reverse Transfer Capacitance 反馈电容(V <sub>GS</sub> =0V, V <sub>DS</sub> =15V, f=1MHz)	C <sub>RSS</sub>	—	71	—	pF
Total Gate Charge 栅极电荷密度 (V <sub>DS</sub> =15V, I <sub>D</sub> =5.6A, V <sub>GS</sub> =10V)	Q <sub>g</sub>	—	17	—	nC
Gate Source Charge 栅源电荷密度 (V <sub>DS</sub> =15V, I <sub>D</sub> =5.6A, V <sub>GS</sub> =10V)	Q <sub>gs</sub>	—	2	—	nC
Gate Drain Charge 栅漏电荷密度 (V <sub>DS</sub> =15V, I <sub>D</sub> =5.6A, V <sub>GS</sub> =10V)	Q <sub>gd</sub>	—	2	—	nC
Turn-ON Delay Time 开启延迟时间 (V <sub>DS</sub> =15V I <sub>D</sub> =5.6A, R <sub>GEN</sub> =3Ω, V <sub>GS</sub> =10V)	t <sub>d(on)</sub>	—	5	—	ns
Turn-ON Rise Time 开启上升时间 (V <sub>DS</sub> =15V I <sub>D</sub> =5.6A, R <sub>GEN</sub> =3Ω, V <sub>GS</sub> =10V)	t <sub>r</sub>	—	28	—	ns
Turn-OFF Delay Time 关断延迟时间 (V <sub>DS</sub> =15V I <sub>D</sub> =5.6A, R <sub>GEN</sub> =3Ω, V <sub>GS</sub> =10V)	t <sub>d(off)</sub>	—	16	—	ns
Turn-OFF Fall Time 关断下降时间 (V <sub>DS</sub> =15V I <sub>D</sub> =5.6A, R <sub>GEN</sub> =3Ω, V <sub>GS</sub> =10V)	t <sub>f</sub>	—	26	—	ns

■ Typical Characteristic Curve 典型特性曲线

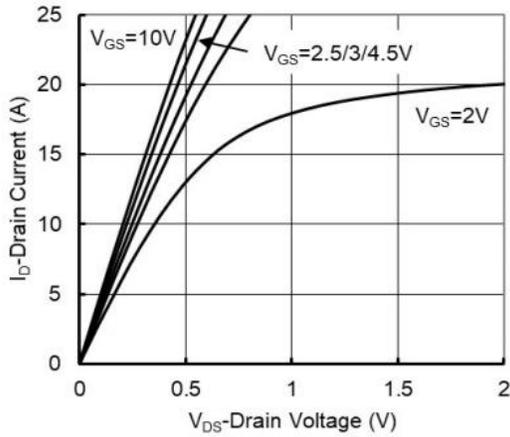


Figure 1: Output Characteristics

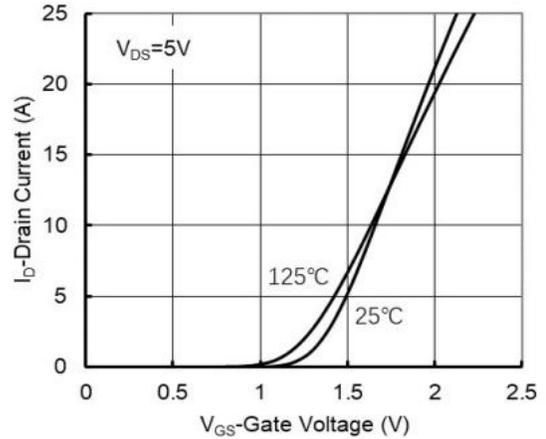


Figure 2: Transfer Characteristics

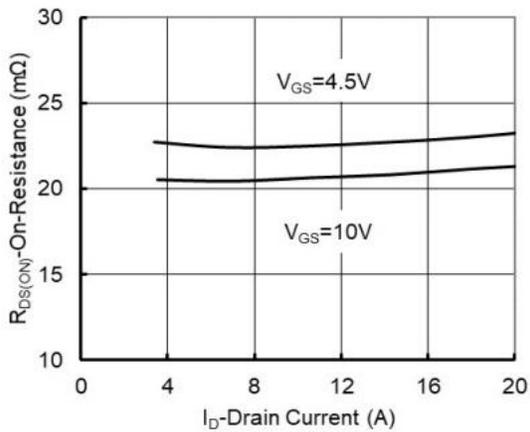


Figure 3: On-Resistance vs. Drain Current

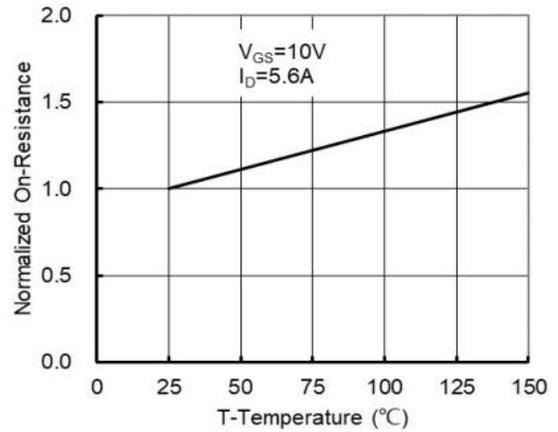


Figure 4: On-Resistance vs. Temperature

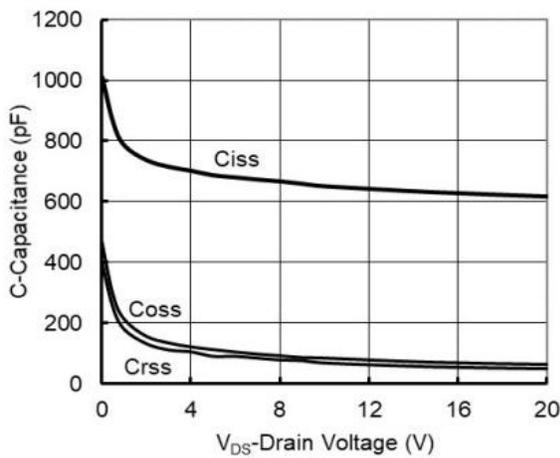


Figure 5: Capacitance Characteristics

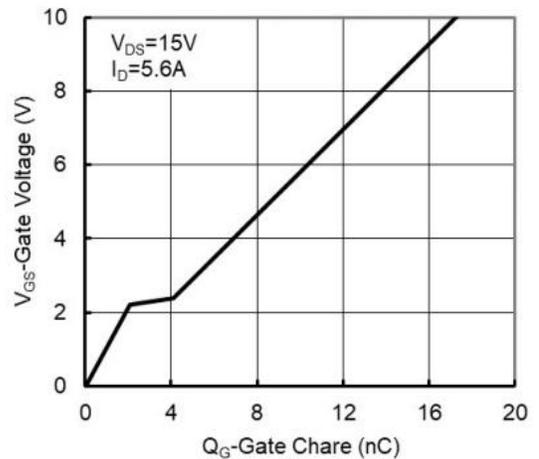


Figure 6: Gate-Charge Characteristics

■ Typical Characteristic Curve 典型特性曲线

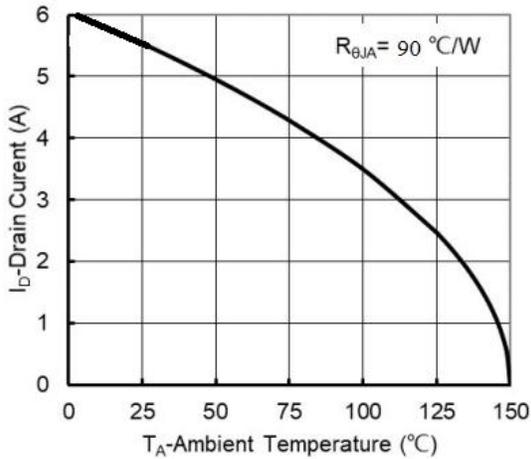


Figure 7: Drain Current vs. Temperature

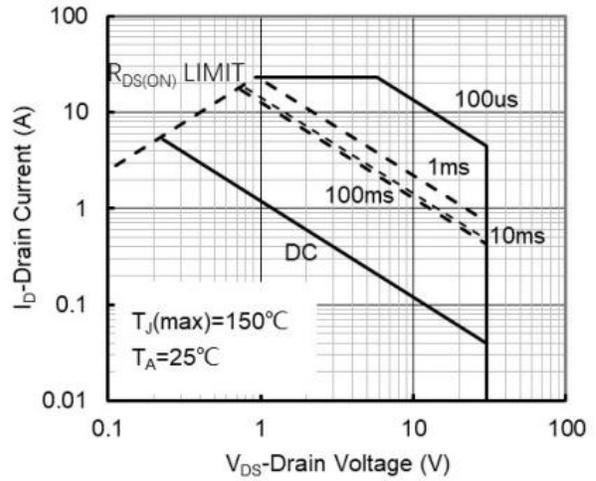


Figure 8: Safe Operating Area

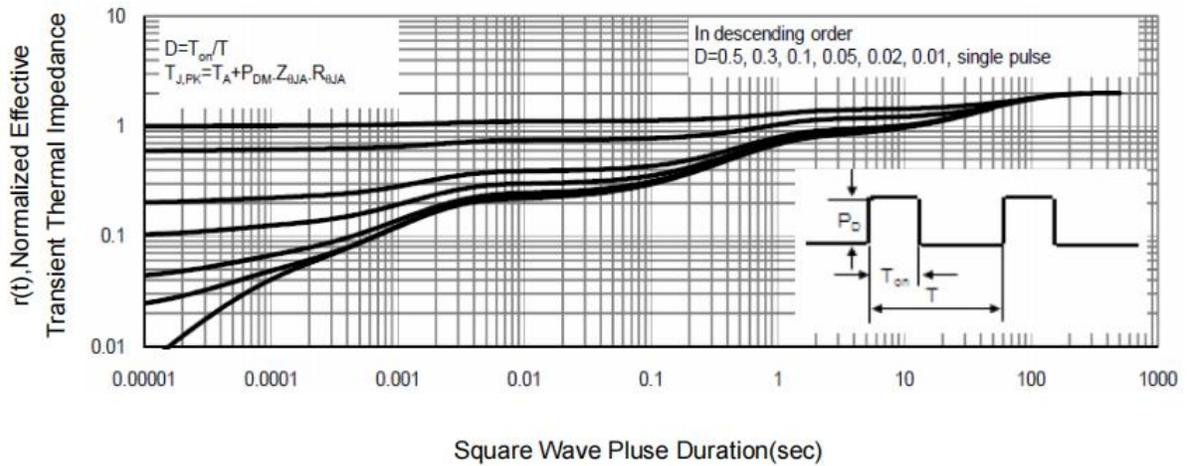
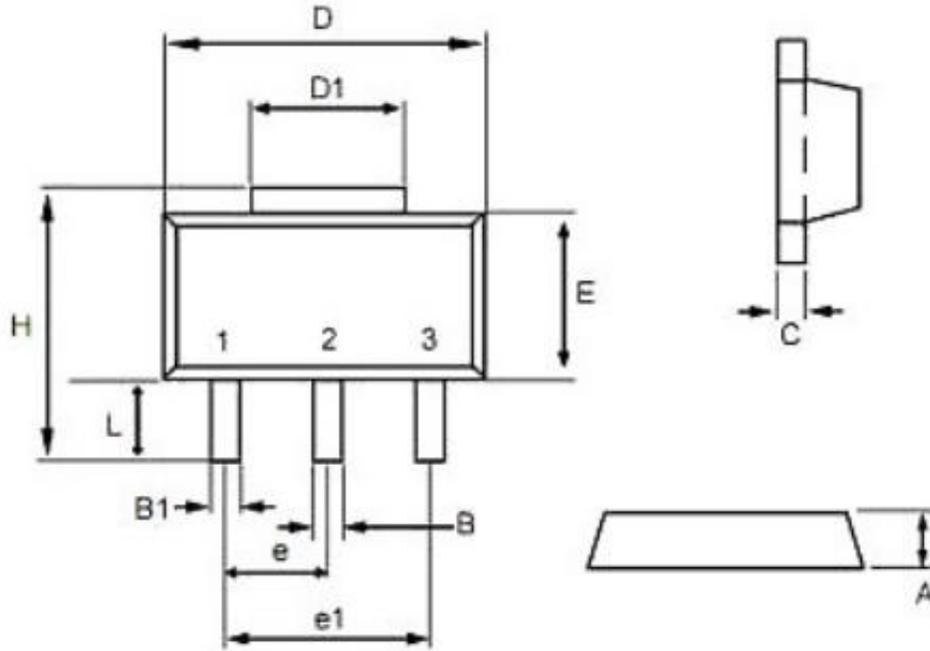


Figure 9: Transient Thermal Response Curve

■ Dimension 外形封装尺寸



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.40	1.60	0.055	0.063
B	0.40	0.56	0.016	0.022
B1	0.35	0.48	0.014	0.019
C	0.35	0.44	0.014	0.017
D	4.40	4.60	0.173	0.181
D1	1.35	1.83	0.053	0.072
e	1.45	1.55	0.057	0.061
e1	2.95	3.05	0.116	0.120
E	2.29	2.60	0.090	0.102
H	3.75	4.25	0.148	0.167
L	0.80	1.20	0.031	0.047